

Notice of References Cited	Application/Control No. 10/005,765	Applicant(s)/Patent Under Reexamination YANG ET AL.	
	Examiner James Mitchell	Art Unit 2827	Page 1 of 1

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	C	US-6,455,398	09-2002	Fonstad et al.	438/459
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NON-PATENT DOCUMENTS

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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.